



**Espacenet**

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**Element transfer method, element arrangement method using the same, and manufacturing method of image display device**

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### **Abstract of TW 546721 (B)**

An element transfer method is provided where elements arrayed on a first substrate are selectively transferred onto a second substrate in which an adhesive resin layer is formed. Laser light is projected onto a rear surface side of the second substrate so that the adhesive resin layer of the second substrate is selectively heated, and the adhesive resin layer is cured so that an element which is to be transferred is bonded to the second substrate. When the laser light is projected onto a rear surface side of a substrate to heat the adhesive resin layer on that part directly or through an element or wire, the adhesive resin layer on the heated part selectively provides adhesive strength. By curing it, only an element which is to be transferred is selectively transferred onto the second substrate, so as to surely and effectively transfer only an object at high precision without affecting other components.

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